INTEGRATED CIRCUITS

DATA SHEET

MB2241

16-bit buffer/line driver (3-State)

Product specification Supersedes data of 1993 Aug 18 IC23 Data Handbook





16-bit buffer/line driver (3-State)

MB2241

FEATURES

- 16-bit bus interface
- Power 3-State
- Multiple V_{CC} and GND pins minimize switching noise
- 3-State buffers
- Output capability: +64mA/-32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Inputs are disabled during 3-State mode

DESCRIPTION

The MB2241 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The MB2241 device is a 16-bit buffer that is ideal for driving bus lines. The device features four Output Enables (1 $\overline{\text{OE}}$, 2 $\overline{\text{OE}}$, 4 $\overline{\text{OE}}$), each controlling four of the 3-State outputs.

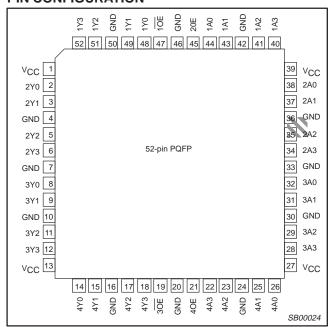
QUICK REFERENCE DATA

SYMBOL	PARAMETER	RAMETER CONDITIONS $T_{amb} = 25^{\circ}C;$ $GND = 0V$		UNIT
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	C _L = 50pF; V _{CC} = 5V	3.0 3.1	ns
C _{IN}	Input capacitance	V _I = 0V or V _{CC}	4	pF
C _{OUT}	Output capacitance	V _O = 0V or V _{CC;} 3-State	7	pF
I _{CCZ}	Total supply current	Outputs disabled; V _{CC} = 5.5V	65	μΑ

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
52-pin plastic Quad Flat Pack	-40°C to +85°C	MB2241 BB	MB2241 BB	SOT379-1

PIN CONFIGURATION



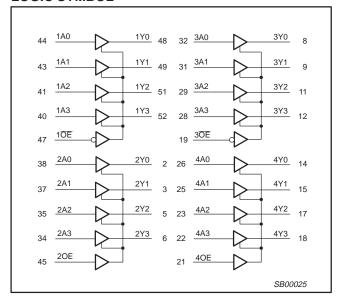
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
44, 43, 41, 40, 38, 37, 35, 34, 32, 31, 29, 28, 26, 25, 23, 22	1A0 – 1A3, 2A0 – 2A3, 3A0 – 3A3, 4A0 – 4A3	Data inputs
14, 15, 17, 18, 8, 9, 11, 12, 2, 3, 5, 6, 48, 49, 51, 52	4Y0 – 4Y3, 3Y0 – 3Y3, 2Y0 – 2Y3, 1Y0 – 1Y3	Data outputs
47, 45, 21, 19	1 <u>0E</u> , 20E, 3 <u>0E</u> , 40E	Output enables
4, 7, 10, 16, 20, 24, 30, 33, 36, 42, 46, 50	GND	Ground (0V)
1, 13, 27, 39	Vcc	Positive supply voltage

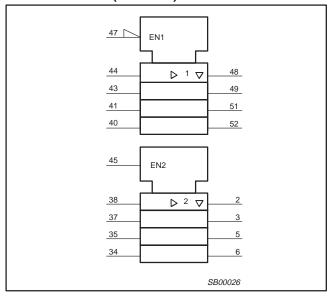
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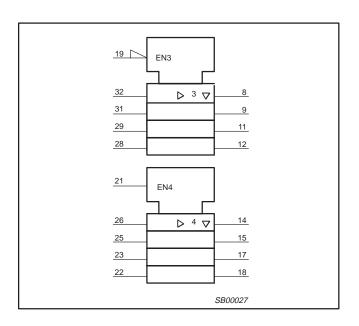
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LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)





FUNCTION TABLE

	INP	ОИТ	PUTS		
1 OE or 3 OE	1An or 3An	20E or 40E	2An or 4An	1Yn or 3Yn	2Yn or 4Yn
L L H	L H X	H H L	L H X	L H Z	L H Z

H = High voltage level

L = Low voltage level

Z = High voltage level-impedance "OFF" state

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ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
I _{OUT}	DC output current	output in Low state	128	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

- 1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
- 3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
		Min	Max	
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level Input voltage		0.8	V
I _{OH}	High-level output current		-32	mA
I _{OL}	Low-level output current		64	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

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DC ELECTRICAL CHARACTERISTICS

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	Tai	_{mb} = +25	°C	T _{amb} =	–40°C 35°C	UNIT
			Min	Тур	Max	Min	Max	
V _{IK}	Input clamp voltage	V _{CC} = 4.5V; I _{IK} = -18mA		-0.9	-1.2		-1.2	V
		$V_{CC} = 4.5V$; $I_{OH} = -3mA$; $V_I = V_{IL}$ or V_{IH}	2.5	2.9		2.5		V
V _{OH}	High-level output voltage	$V_{CC} = 5.0V$; $I_{OH} = -3mA$; $V_I = V_{IL}$ or V_{IH}	3.0	3.4		3.0		V
		$V_{CC} = 4.5V$; $I_{OH} = -32mA$; $V_I = V_{IL}$ or V_{IH}	2.0	2.4		2.0		V
V _{OL}	Low-level output voltage	$V_{CC} = 4.5V$; $I_{OL} = 64mA$; $V_I = V_{IL}$ or V_{IH}		0.42	0.55		0.55	V
I _I	Input leakage current	V _{CC} = 5.5V; V _I = GND or 5.5V		±0.01	±1.0		±1.0	μΑ
I _{OFF}	Power-off leakage current	$V_{CC} = 0.0V$; V_O or $V_I \le 4.5V$		±5.0	±100		±100	μΑ
I _{PU} /I _{PU}	Power-up/down 3-State output current	$V_{\underline{CC}}$ = 2.0V; V_{O} = 0.5V; V_{I} = GND or V_{CC} ; V_{OE} = V_{CC} ; V_{OE} = GND		±5.0	±50		±50	μА
I _{OZH}	3-State output High current	$V_{CC} = 5.5V; V_{O} = 2.7V; V_{I} = V_{IL} \text{ or } V_{IH}$		5.0	50		50	μΑ
I _{OZL}	3-State output Low current	$V_{CC} = 5.5V; V_{O} = 0.5V; V_{I} = V_{IL} \text{ or } V_{IH}$		-5.0	-50		-50	μΑ
I _{CEX}	Output high leakage current	V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = GND or V_{CC}		5.0	50		50	μΑ
Io	Output current ¹	V _{CC} = 5.5V; V _O = 2.5V	-50	-70	-180	-50	-180	mA
I _{CCH}		V_{CC} = 5.5V; Outputs High, V_{I} = GND or V_{CC}		65	250		250	μΑ
I _{CCL}	Quiescent supply current	V_{CC} = 5.5V; Outputs Low, V_I = GND or V_{CC}		48	60		60	mA
I _{CCZ}		V_{CC} = 5.5V; Outputs 3-State; V_{I} = GND or V_{CC}		65	250		250	μА
Δl _{CC}	Additional supply current per input pin ²	Outputs enabled, one input at 3.4V, other inputs at V_{CC} or GND; V_{CC} = 5.5V		0.5	1.5		1.5	mA

NOTES:

- 1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- 2. This is the increase in supply current for each input at 3.4V.

AC CHARACTERISTICS

 $\label{eq:gnd} \text{GND} = \text{0V}; \ t_{\text{R}} = t_{\text{F}} = \text{2.5ns}; \ C_{\text{L}} = \text{50pF}, \ R_{\text{L}} = \text{500}\Omega$

					LIMIT	rs		
SYMBOL	PARAMETER	WAVEFORM	T ₂	_{amb} = +25° CC = +5.0°	C V	T _{amb} = -40° V _{CC} = +5.	°C to +85°C .0V ±0.5V	UNIT
			Min	Тур	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	1	1.2 1.2	3.0 3.1	4.5 4.5	1.2 1.2	5.1 5.1	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	2	1.3 1.8	3.7 4.8	6.3 6.8	1.3 1.8	6.9 7.4	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low level	2	1.3 1.2	3.9 3.4	5.9 5.2	1.3 1.2	6.7 5.8	ns

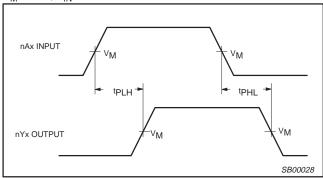
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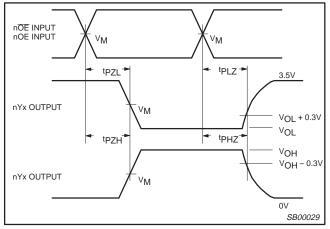
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AC WAVEFORMS

 $V_M = 1.5V$, $V_{IN} = GND$ to 3.0V

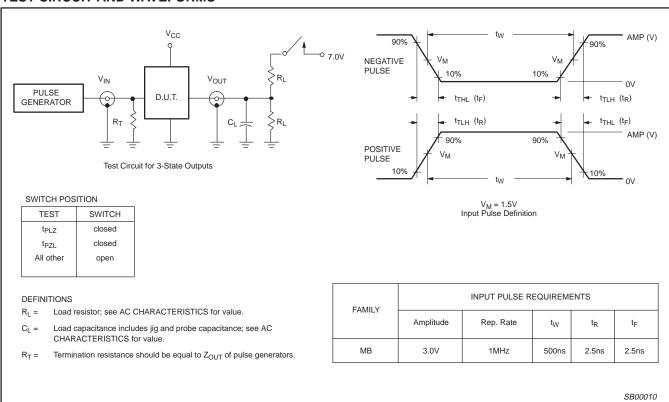


Waveform 1. Waveforms Showing the Input (nAx) to Output (nYx) Propagation Delays

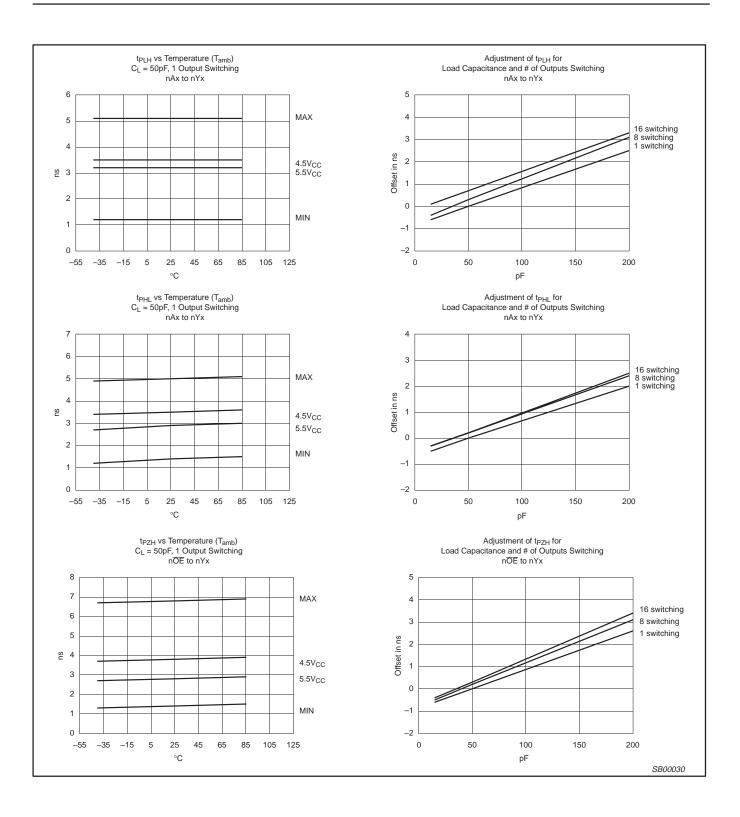


Waveform 2. Waveforms Showing the 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORMS

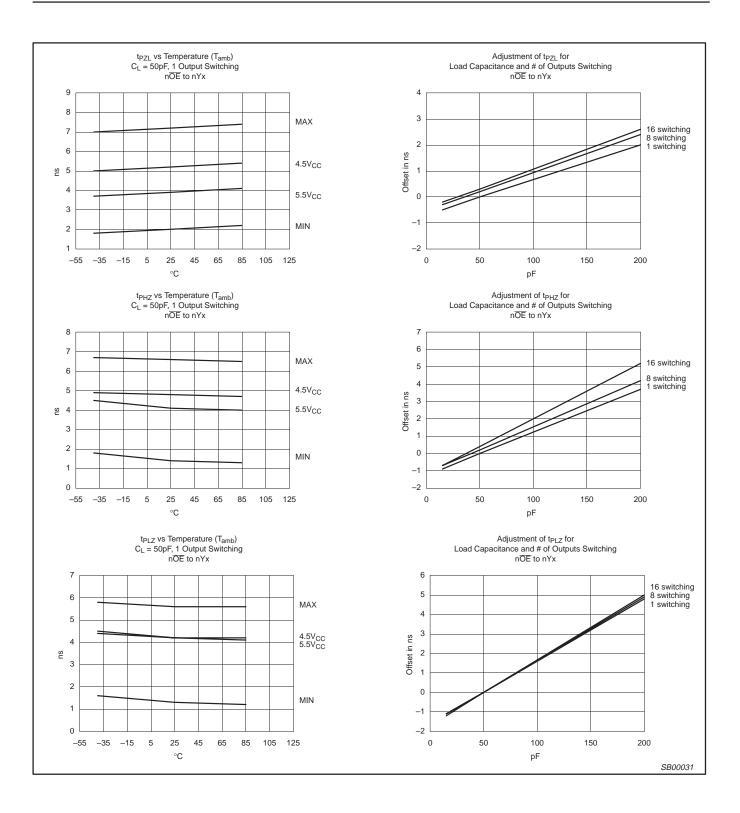


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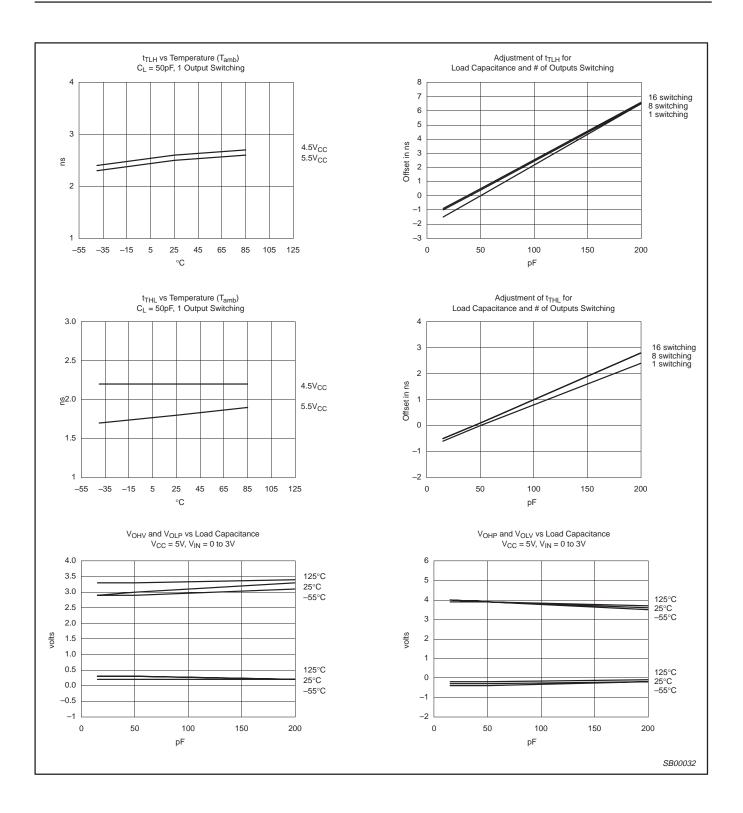


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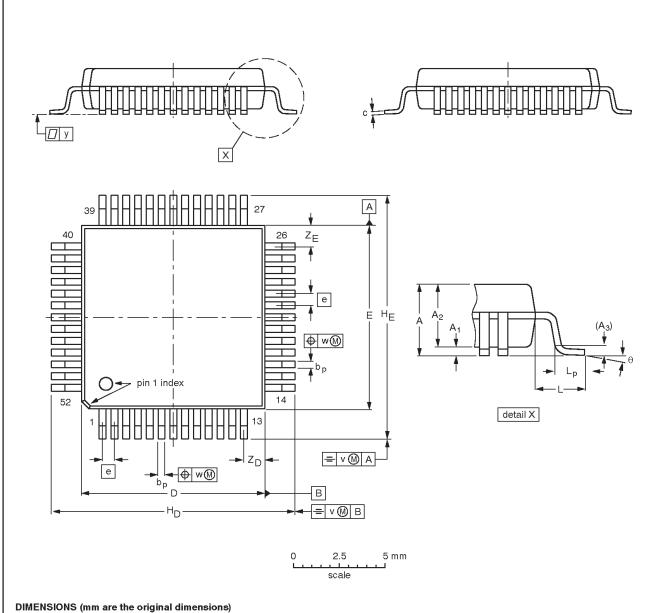
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QFP52: plastic quad flat package; 52 leads (lead length 1.6 mm); body 10 x 10 x 2.0 mm

SOT379-1



UNIT	A max.	Α1	A ₂	А3	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	H _D	HE	L	Lp	v	w	у	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	2.45	0.45 0.25	2.10 1.95	0.25	0.38 0.22	0.23 0.13	10.1 9.9	10.1 9.9	0.65	13.45 12.95	13.45 12.95	1.60	0.95 0.65	0.20	0.12	0.10	1.24 0.95	1.24 0.95	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT379-1		MO-108			-95-02-04- 97-08-04

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NOTES

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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